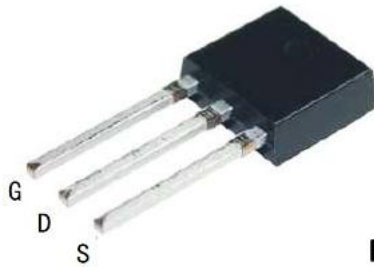
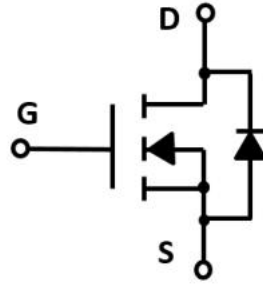


## N-Channel Super Junction Power MOSFET



**TO-251**



### Product Summary

- $V_{DS}$  600V
- $I_D$  5A
- $R_{DS(ON)}$  ( at  $V_{GS}=10V$ ) <840 mohm
- 100% UIS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Multi-EPI Super Junction MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$

### Applications

- Power factor correction(PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply(UPS)

### ■ Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	$V_{DS}$	600	V
Gate-source Voltage	$V_{GS}$	$\pm 30$	V
Drain Current	$I_D$	$T_C=25^\circ\text{C}$	5
		$T_C=100^\circ\text{C}$	3
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	45	A
Avalanche energy, Single pulse <sup>B</sup>	$E_{AS}$	624	mJ
Avalanche energy, repetitive	$E_{AR}$	150	mJ
MOSFET dv/dt ruggedness	dv/dt	11	V/ns
Reverse diode dv/dt, $V_{DS}=0\dots 480\text{ V}$ , $I_{SD}\leq I_D$	dv/dt	15	V/ns
Total Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$	69
		$T_C=100^\circ\text{C}$	28
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	1.06	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	$^\circ\text{C}$

### ■ Ordering Information

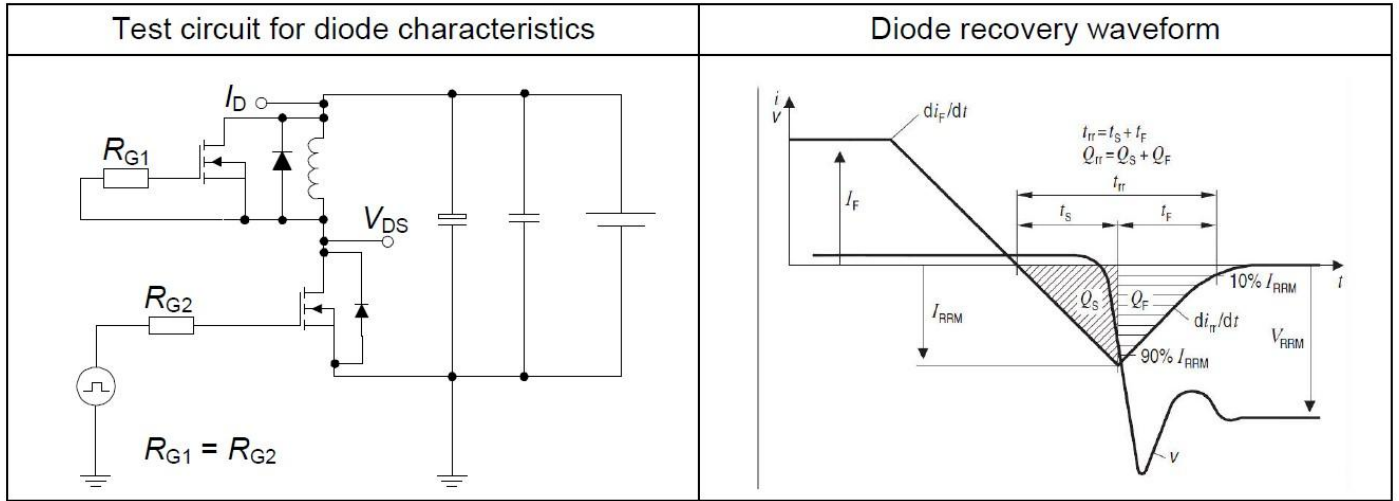
PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
LMU60R840A		YJU60R840A	75	4950	29700	Tube

## ■ Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

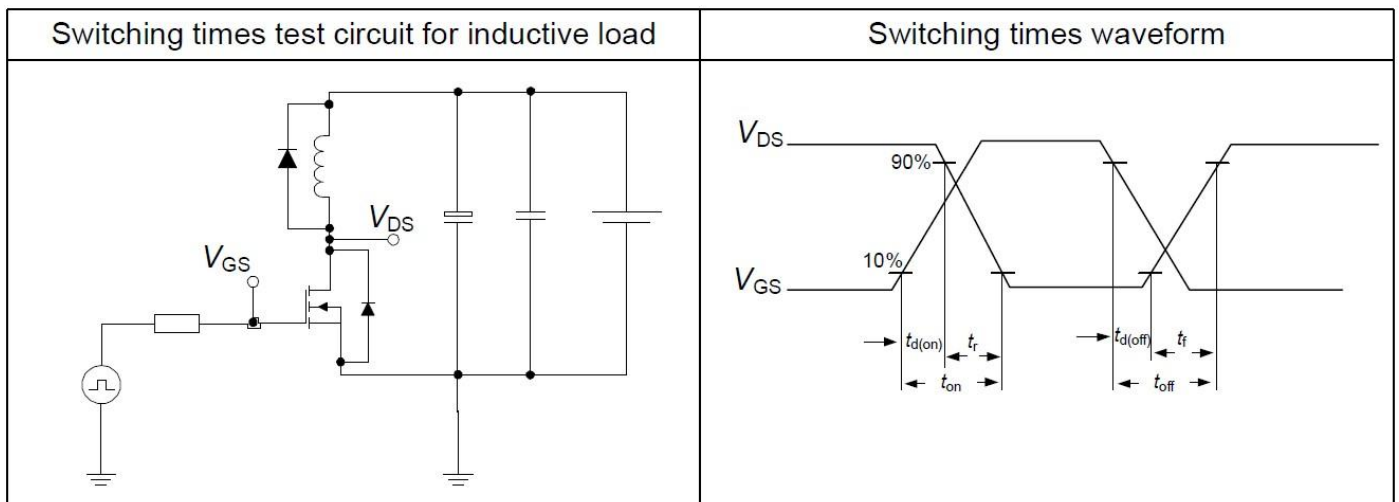
Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =1mA	600			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V			0.1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±30V, V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	2.8		4.2	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> =2.5A		750	840	mΩ
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =3.8A, V <sub>GS</sub> =0V		0.81		V
Maximum Body-Diode Continuous Current	I <sub>S</sub>				8	A
Gate resistance(Intrinsic)	R <sub>G</sub>	F=1MHz, open drain		12.1		Ω
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=10KHZ		550		pF
Output Capacitance	C <sub>oss</sub>			39		
Reverse Transfer Capacitance	C <sub>rss</sub>			2.8		
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =13V, V <sub>DS</sub> =400V, I <sub>D</sub> =2.5A		2.0		nC
Gate-Source Charge	Q <sub>gs</sub>			2.6		
Gate-Drain Charge	Q <sub>gd</sub>			10.7		
Reverse Recovery Charge	Q <sub>rr</sub>	V <sub>R</sub> =400A, I <sub>F</sub> =2.2A, di/dt=100A/us		880		A
Peak reverse recovery current	I <sub>rrm</sub>			10		
Reverse Recovery Time	t <sub>rr</sub>			125		
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>DD</sub> =400V, R <sub>G</sub> =10Ω, I <sub>D</sub> =2.5A		27		ns
Turn-on Rise Time	t <sub>r</sub>			31		
Turn-off Delay Time	t <sub>D(off)</sub>			41		
Turn-off fall Time	t <sub>f</sub>			29		

■ Test Circuits

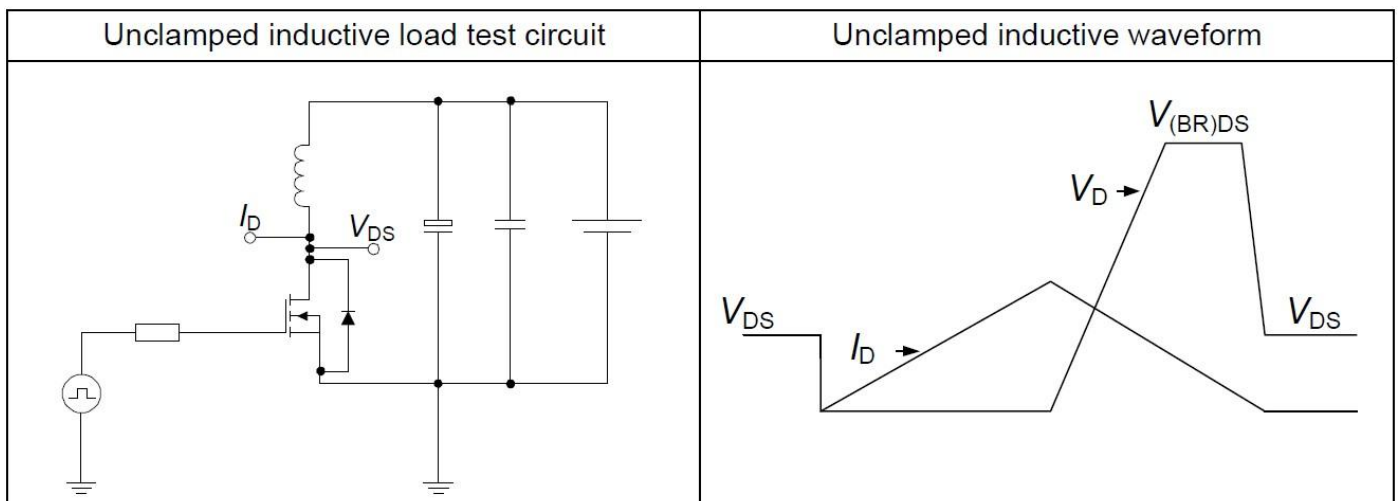
Diode characteristics



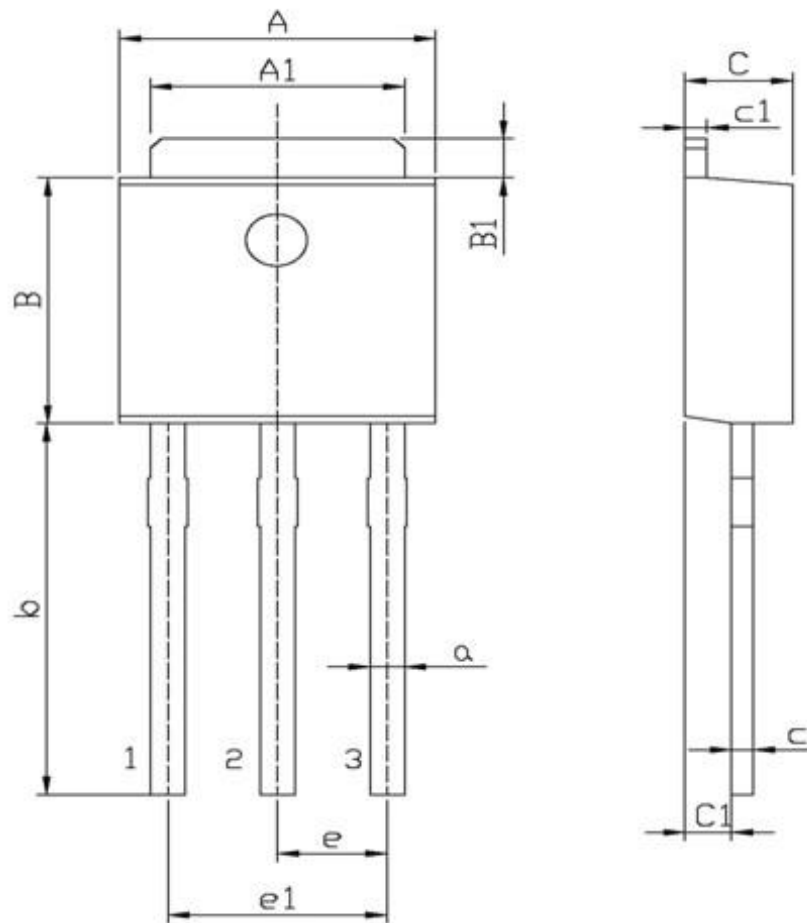
Switching times



Unclamped inductive load



■ TO-251 Package information



单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	6.45	6.75	a	0.50	0.70
A1	5.10	5.50	b	9.00	9.40
B	5.95	6.25	c	0.45	0.55
B1	0.95	1.25	c1	0.45	0.55
C	2.20	2.40	e	2.24	2.34
C1	0.95	1.15	e1	4.43	4.73